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S7G2 MCU (High-performance MCU)

32-bit ARM® Cortex®-M4 microcontroller

Leading performance 240-MHz ARM Cortex-M4 microcontroller, up to 4-MB code flash memory, 640-KB SRAM, Graphics LCD Controller, 2D Drawing Engine, Capacitive Touch Sensing Unit, Ethernet MAC Controller with IEEE 1588 PTP, USB 2.0 High-Speed, USB 2.0 Full-Speed, SDHI, Quad SPI, security and safety features, and advanced analog.

Features

■ ARM Cortex-M4 Core with Floating Point Unit (FPU)
- ARMv7E-M architecture with DSP instruction set
- Maximum operating frequency: 240 MHz
- Support for 4-GB address space
- On-chip debugging system: JTAG, SWD, and ETM
- Boundary scan and ARM Memory Protection Unit (MPU)

■ Memory
- Up to 4-MB code flash memory (80 MHz zero wait states)
- 64-KB data flash memory (up to 100,000 erase/write cycles)
- Up to 640-KB SRAM
- Flash Cache (FCACHE)
- Memory Protection Units (MPU)
- Memory Mirror Function (MMF)
- 128-bit unique ID

■ Connectivity
- Ethernet MAC Controller (ETHERC) × 2
- Ethernet DMA Controller (EDMAC)
- Ethernet PTP Controller (EPTPC)
- USB 2.0 High-Speed Module (USBHS)
  - On-chip transceiver
  - USB battery charge version 1.2 supported
- USB 2.0 Full-Speed Module (USBFS)
  - On-chip transceiver
- Serial Communications Interface (SCI) with FIFO × 10
- Serial Peripheral Interface (SPI) × 2
- I^2C Bus Interface (IIC) × 3
- CAN module (CAN) × 2
- Serial Sound Interface (SSI) × 2
- SD/MMC Host Interface (SDHI) × 2
- Quad Serial Peripheral Interface (QSPI)
- IrDA interface
- Sampling Rate Converter (SRC)
- External memory bus
  - 8-bit and 16-bit address width
  - SDRAM support

■ Analog
- 12-Bit A/D Converter (ADC12) with 3 sample-and-hold circuits each, x2
- 12-Bit D/A Converter (DAC12) × 2
- High-Speed Analog Comparator (ACMPHS) × 6
- Programmable Gain Amplifier (PGA) × 6
- Temperature sensor (TSN)

■ Timers
- General PWM Timer 32-Bit Enhanced High Resolution (GPT32EH) × 4
- General PWM Timer 32-Bit Enhanced (GPT32E) × 4
- General PWM Timer 32-Bit (GPT32) × 6
- Asynchronous General-Purpose Timer (AGT) × 2
- Watchdog Timer (WDT)

■ Safety
- SRAM parity error check
- Flash area protection
- ADC self-diagnosis function
- Clock Frequency Accuracy Measurement Circuit (CAC)
- Cyclic Redundancy Check (CRC) calculator
- Data Operation Circuit (DOC)
- Port Output Enable for GPT (POEG)
- Independent Watchdog Timer (IWDT)
- GPIO readback level detection
- Register write protection
- Main oscillator stop detection
- Illegal memory access

■ System and Power Management
- Low-power modes
- Switching regulator
- Realtime Clock (RTC) with calendar and VBATT support
- Event Link Controller (ELC)
- DMA Controller (DMAC) × 8
- Data Transfer Controller (DTC)
- Key interrupt function (KINT)
- Power-on reset
- Low Voltage Detection (LVD) with voltage settings

■ Security and Encryption
- AES128/192/256
- 3DES/ARC4
- SHA1/SHA224/SHA256
- GHASH
- RSA/DSA
- True Random Number Generator (TRNG)

■ Human Machine Interface (HMI)
- Graphics LCD Controller (GLCDC)
- JPEG Codec
- 2D Drawing Engine (DRW)
- Capacitive Touch Sensing Unit (CTSU)
- Parallel Data Capture Unit (PDC)

■ Multiple Clock Sources
- Main clock oscillator (MOSC) (8 to 24 MHz)
- Sub-clock oscillator (SOSC) (32.768 kHz)
- High-speed on-chip oscillator (HOCO) (16/18/20 MHz)
- Middle-speed on-chip oscillator (MOCO) (8 MHz)
- Low-speed on-chip oscillator (LOCO) (32.768 kHz)
- Independent Watchdog Timer OCO (15 kHz)
- Clock trim function for HOCO/MOCO/LOCO
- Clock out support

■ General-Purpose I/O Ports
- Up to 172 input/output pins
  - Up to 9 CMOS input
  - Up to 163 CMOS input/output
    - Up to 22 5-V tolerant input/output
    - Up to 24 high current (20 mA)

■ Operating Voltage
- VCC: 2.7 to 3.6 V

■ Operating Temperature and Packages
- Ta = –40°C to +85°C
  - 224-pin BGA (13 mm × 13 mm, 0.8 mm pitch)
  - 176-pin BGA (13 mm × 13 mm, 0.8 mm pitch)
  - 145-pin LGA (7 mm × 7 mm, 0.5 mm pitch)
- Ta = –40°C to +105°C
  - 176-pin LQFP (24 mm × 24 mm, 0.5 mm pitch)
  - 144-pin LQFP (20 mm × 20 mm, 0.5 mm pitch)
  - 100-pin LQFP (14 mm × 14 mm, 0.5 mm pitch)

1. Overview

The S7G2 MCU integrates multiple series of software- and pin-compatible ARM®-based 32-bit MCUs that share the same set of Renesas peripherals to facilitate design scalability and efficient platform-based product development.

The MCU provides a high-performance ARM Cortex®-M4 core running up to 240 MHz with the following features:

- Up to 4-MB code flash memory
- 640-KB SRAM
- Graphics LCD Controller (GLCDC)
- 2D Drawing Engine (DRW)
- Capacitive Touch Sensing Unit (CTSU)
- Ethernet MAC Controller (ETHERC) with IEEE 1588 PTP, USBFS, USBHS, SD/MMC Host Interface
- Quad Serial Peripheral Interface (QSPI)
- Security and safety features
- Analog peripherals.

1.1 Function Outline

Table 1.1 ARM core

Feature	Functional description
ARM Cortex-M4	• Maximum operating frequency: up to 240 MHz • ARM Cortex-M4 core: - Revision: r0p1-01rel0 - ARMv7E-M architecture profile - Single precision floating point unit compliant with the ANSI/IEEE Std 754-2008 • ARM Memory Protection Unit (MPU): - ARMv7 Protected Memory System Architecture - 8 protect regions • SysTick timer: - Driven by LOCO clock

Table 1.2 Memory

Feature	Functional description
Code flash memory	Maximum 4 MB of code flash memory. See section 54, Flash Memory in User's Manual.
Data flash memory	64 KB of data flash memory. See section 54, Flash Memory in User's Manual.
Memory Mirror Function (MMF)	The MMF can be configured to mirror the wanted application image load address in code flash memory to the application image link address in the 23-bit unused memory space (memory mirror space addresses). Your application code is developed and linked to run from this MMF destination address. The application code does not need to know the load location where it is stored in code flash memory. See section 5, Memory Mirror Function (MMF) in User's Manual.
SRAM	On-chip high-speed SRAM providing either parity-bit or double-bit error detection (DED). The first 32 KB of SRAM0 is subject to DED. Parity check is performed for other areas. See section 52, SRAM in User's Manual.
Standby SRAM	On-chip SRAM that can retain data in Deep Software Standby mode. See section 53, Standby SRAM in User's Manual.

Table 1.3 System (1/2)

Feature	Functional description
Operating modes	Two operating modes: - Single-chip mode - SCI or USB boot mode. See section 3, Operating Modes in User's Manual.

Table 1.3 System (2/2)

Feature	Functional description
Resets	14 resets: • RES pin reset • Power-on reset • Voltage monitor reset 0 • Voltage monitor reset 1 • Voltage monitor reset 2 • Independent Watchdog Timer reset • Watchdog Timer reset • Deep Software Standby reset • SRAM parity error reset • SRAM DED error reset • Bus master MPU error reset • Bus slave MPU error reset • Stack pointer error reset • Software reset. See section 6, Resets in User's Manual.
Low Voltage Detection (LVD)	The Low Voltage Detection (LVD) function monitors the voltage level input to the VCC pin, and the detection level can be selected in the software program. See section 8, Low Voltage Detection (LVD) in User's Manual.
Clocks	• Main clock oscillator (MOSC) • Sub-clock oscillator (SOSC) • High-speed on-chip oscillator (HOCO) • Middle-speed on-chip oscillator (MOCO) • Low-speed on-chip oscillator (LOCO) • PLL frequency synthesizer • Independent Watchdog Timer (WDT) on-chip oscillator • Clock out supports. See section 9, Clock Generation Circuit in User's Manual.
Clock Frequency Accuracy Measurement Circuit (CAC)	The CAC checks the system clock frequency with a reference clock signal by counting the number of pulses of the system clock to be measured. The reference clock can be provided externally through a CACREF pin or internally from various on-chip oscillators. Event signals can be generated when the clock does not match or measurement ends. This feature is particularly useful in implementing a fail-safe mechanism for home and industrial automation applications. See section 10, Clock Frequency Accuracy Measurement Circuit (CAC) in User's Manual.
Low-power modes	Power consumption can be reduced in multiple ways, including by setting clock dividers, controlling EBCLK output, controlling SDCLK output, stopping modules, selecting power control mode in normal operation, and transitioning to low-power modes. See section 11, Low-Power Modes in User's Manual.
Battery backup function	A battery backup function is provided for partial powering by a battery. The battery-powered area includes the RTC, SOSC, backup memory, and switch between VCC and VBATT. See section 12, Battery Backup Function in User's Manual.
Register write protection	The register write protection function protects important registers from being overwritten because of software errors. See section 13, Register Write Protection in User's Manual.
Memory Protection Unit (MPU)	Two MPUs and a CPU stack pointer monitor functions are provided for memory protection. See section 16, Memory Protection Unit (MPU) in User's Manual.
Watchdog Timer (WDT)	The WDT is a 14-bit down-counter. It can be used to reset the MCU when the counter underflows because the system has run out of control and is unable to refresh the WDT. In addition, a non-maskable interrupt or interrupt can be generated by an underflow. A refresh-permitted period can be set to refresh the counter and be used as the condition for detecting when the system runs out of control. See section 27, Watchdog Timer (WDT) in User's Manual.
Independent Watchdog Timer (IWDT)	The IWDT consists of a 14-bit down-counter that must be serviced periodically to prevent counter underflow. The IWDT provides functionality to reset the MCU or to generate a non-maskable interrupt or interrupt for a timer underflow. Because the timer operates with an independent, dedicated clock source, it is particularly useful in returning the MCU to a known state as a fail safe mechanism when the system runs out of control. The IWDT can be triggered automatically on a reset, underflow, or refresh error, or by a refresh of the count value in the registers. See section 28, Independent Watchdog Timer (IWDT) in User's Manual.

Table 1.4 Interrupt control

Feature	Functional description
Interrupt Controller Unit (ICU)	The ICU controls which event signals are linked to the NVIC/DTC module and DMAC module. The ICU also controls NMI interrupts. See section 14, Interrupt Controller Unit (ICU) in User's Manual.

Table 1.5 Event link

Feature	Functional description
Event Link Controller (ELC)	The ELC uses the interrupt requests generated by various peripheral modules as event signals to connect them to different modules, enabling direct interaction between the modules without CPU intervention. See section 19, Event Link Controller (ELC) in User's Manual.

Table 1.6 Direct memory access

Feature	Functional description
Data Transfer Controller (DTC)	A DTC module is provided for transferring data when activated by an interrupt request. See section 18, Data Transfer Controller (DTC) in User's Manual.
DMA Controller (DMAC)	An 8-channel DMAC module is provided for transferring data without the CPU. When a DMA transfer request is generated, the DMAC transfers data stored at the transfer source address to the transfer destination address. See section 17, DMA Controller (DMAC) in User's Manual.

Table 1.7 External bus interface

Feature	Functional description
External buses	• CS area (EXBIU): Connected to the external devices (external memory interface) • SDRAM area (EXBIU): Connected to the SDRAM (external memory interface) • QSPI area (EXBIUT2): Connected to the QSPI (external device interface).

Table 1.8 Timers

Feature	Functional description
General PWM Timer (GPT)	The GPT is a 32-bit timer with 14 channels. PWM waveforms can be generated by controlling the up-counter, down-counter, or up- and down-counter. In addition, PWM waveforms can be generated for controlling brushless DC motors. The GPT can also be used as a general-purpose timer. See section 23, General PWM Timer (GPT) in User's Manual.
Port Output Enable for GPT (POEG)	Use the Port Output Enable (POEG) function to place the General PWM Timer (GPT) output pins in the output disable state.
Asynchronous General-Purpose Timer (AGT)	The AGT is a 16-bit timer that can be used for pulse output, external pulse width or period measurement, and counting of external events. This 16-bit timer consists of a reload register and a down-counter. The reload register and the down-counter are allocated to the same address, and can be accessed with the AGT register. See section 25, Asynchronous General-Purpose Timer (AGT) in User's Manual.
Realtime Clock (RTC)	The RTC has two counting modes, calendar count mode and binary count mode, that are controlled by the register settings. For calendar count mode, the RTC has a 100-year calendar from 2000 to 2099 and automatically adjusts dates for leap years. For binary count mode, the RTC counts seconds and retains the information as a serial value. Binary count mode can be used for calendars other than the Gregorian (Western) calendar. See section 26, Realtime Clock (RTC) in User's Manual.

Table 1.9 Communication interfaces (1/2)

Feature	Functional description
Serial Communications Interface (SCI)	The SCI is configurable to five asynchronous and synchronous serial interfaces: • Asynchronous interfaces (UART and Asynchronous Communications Interface Adapter (ACIA)) • 8-bit clock synchronous interface • Simple IIC (master-only) • Simple SPI • Smart card interface. The smart card interface complies with the ISO/IEC 7816-3 standard for electronic signals and transmission protocol. Each SCI has FIFO buffers to enable continuous and full-duplex communication, and the data transfer speed can be configured independently using an on-chip baud rate generator. See section 34, Serial Communications Interface (SCI) in User's Manual.
IrDA Interface (IrDA)	The IrDA interface sends and receives IrDA data communication waveforms in cooperation with the SCI1 based on the IrDA (Infrared Data Association) standard 1.0. See section 35, IrDA Interface in User's Manual.
I^2C Bus Interface (IIC)	The three-channel IIC conforms with and provides a subset of the NXP I^2C bus (Inter-Integrated Circuit bus) interface functions. See section 36, I^2C Bus Interface (IIC) in User's Manual.
Serial Peripheral Interface (SPI)	Two independent SPI channels are capable of high-speed, full-duplex synchronous serial communications with multiple processors and peripheral devices. See section 38, Serial Peripheral Interface (SPI) in User's Manual.
Serial Sound Interface (SSI)	The SSI peripheral provides functionality to interface with digital audio devices for transmitting PCM audio data over a serial bus with the MCU. The SSI supports an audio clock frequency of up to 50 MHz, and can be operated as a slave or master receiver, transmitter, or transceiver to suit various applications. The SSI includes 8-stage FIFO buffers in the receiver and transmitter, and supports interrupts and DMA-driven data reception and transmission. See section 41, Serial Sound Interface (SSI) in User's Manual.
Quad Serial Peripheral Interface (QSPI)	The QSPI is a memory controller for connecting a serial ROM (nonvolatile memory such as a serial flash memory, serial EEPROM, or serial FeRAM) that has an SPI-compatible interface. See section 39, Quad Serial Peripheral Interface (QSPI) in User's Manual.
Controller Area Network (CAN) Module	The CAN module provides functionality to receive and transmit data using a message-based protocol between multiple slaves and masters in electromagnetically-noisy applications. The CAN module complies with the ISO 11898-1 (CAN 2.0A/CAN 2.0B) standard and supports up to 32 mailboxes, which can be configured for transmission or reception in normal mailbox and FIFO modes. Both standard (11-bit) and extended (29-bit) messaging formats are supported. See section 37, Controller Area Network (CAN) Module in User's Manual.
USB 2.0 Full-Speed Module (USBFS)	Full-Speed USB controller that can operate as a host controller or device controller. The module supports full-speed and low-speed (host controller only) transfer as defined in Universal Serial Bus Specification 2.0. The module has an internal USB transceiver and supports all of the transfer types defined in Universal Serial Bus Specification 2.0. The USB has buffer memory for data transfer, providing a maximum of 10 pipes. Pipes 1 to 9 can be assigned any endpoint number based on the peripheral devices used for communication or based on your system. See section 32, USB 2.0 Full-Speed Module (USBFS) in User's Manual.
USB 2.0 High-Speed Module (USBHS)	High-Speed USB controller that can operate as a host controller or a device controller. As a host controller, the USBHS supports high-speed transfer, full-speed transfer, and low-speed transfer as defined in Universal Serial Bus Specification 2.0. As a device controller, the USBHS supports high-speed transfer and full-speed transfer as defined in Universal Serial Bus Specification 2.0. The USBHS has an internal USB transceiver and supports all of the transfer types defined in Universal Serial Bus Specification 2.0. The USBHS has FIFO buffers for data transfer, providing a maximum of 10 pipes. Any endpoint number can be assigned to pipes 1 to 9, based on the peripheral devices or your system for communication. See section 33, USB 2.0 High-Speed Module (USBHS) in User's Manual.

Table 1.9 Communication interfaces (2/2)

Feature	Functional description
Ethernet MAC with IEEE 1588 PTP (ETHERC)	Two-channel Ethernet MAC Controller (ETHERC) compliant with the Ethernet/IEEE802.3 Media Access Control (MAC) layer protocol. Each ETHERC channel provides one channel of the MAC layer interface, connecting the MCU to the physical layer LSI (PHY-LSI) that allows transmission and reception of frames compliant with the Ethernet and IEEE802.3 standards. The ETHERC is connected to the Ethernet DMA Controller (EDMAC) so data can be transferred without using the CPU. To handle timing and synchronization between devices, an on-chip Precision Time Protocol (PTP) module for the Ethernet PTP Controller (EPTPC) applies the PTP defined in the IEEE 1588-2008 version 2.0 standard. The EPTPC is composed of: • Synchronization Frame Processing units (SYNFP0 and SYNFP1) • A Packet Relation Controller unit (PRC-TC) • A Statistical Time Correction Algorithm unit (STCA). Use the EPTPC in combination with the on-chip Ethernet MAC Controller (ETHERC) and the DMA Controller for the PTP Ethernet Controller (PTPEDMAC). See section 29, Ethernet MAC Controller (ETHERC) in User's Manual.
SD/MMC Host Interface (SDHI)	The SDHI and MultiMediaCard (MMC) interface provide the functionality required to connect a variety of external memory cards to the MCU. The SDHI supports both 1- and 4-bit buses for connecting memory cards that support SD, SDHC, and SDXC formats. When developing host devices that are compliant with the SD Specifications, you must comply with the SD Host/Ancillary Product License Agreement (SD HALA). The MMC interface supports 1-, 4-, and 8-bit MMC buses that provide eMMC 4.51 (JEDEC Standard JESD 84-B451) device access. This interface also provides backward compatibility and supports high-speed SDR transfer modes. See section 43, SD/MMC Host Interface (SDHI) in User's Manual.

Table 1.10 Analog

Feature	Functional description
12-Bit A/D Converter (ADC12)	Up to two successive approximation 12-Bit A/D Converters are provided. In unit 0, up to 13 analog input channels are selectable. In unit 1, up to 12 analog input channels, the temperature sensor output, and an internal reference voltage are selectable for conversion. The A/D conversion accuracy is selectable from 12-, 10-, and 8-bit conversion, making it possible to optimize the tradeoff between speed and resolution in generating a digital value. See section 46, 12-Bit A/D Converter (ADC12) in User's Manual.
12-Bit D/A Converter (DAC12)	The DAC12 D/A converts data and includes an output amplifier. See section 47, 12-Bit D/A Converter (DAC12) in User's Manual.
Temperature sensor (TSN)	The on-chip temperature sensor can determine and monitor the die temperature for reliable operation of the device. The sensor outputs a voltage directly proportional to the die temperature, and the relationship between the die temperature and the output voltage is linear. The output voltage is provided to the ADC12 for conversion and can also be used by the end application. See section 48, Temperature Sensor (TSN) in User's Manual.
High-Speed Analog Comparator (ACMPHS)	Analog comparators can be used to compare a test voltage with a reference voltage and to provide a digital output based on the conversion result. Both the test and reference voltages can be provided to the comparator from internal sources such as the DAC12 output and internal reference voltage, and an external source with or without an internal PGA. Such flexibility is useful in applications that require go/no-go comparisons to be performed between analog signals without necessarily requiring A/D conversion. See section 49, High-Speed Analog Comparator (ACMPHS) in User's Manual.

Table 1.11 Human machine interfaces (1/2)

Feature	Functional description
Key interrupt function (KINT)	A key interrupt can be generated by setting the Key Return Mode register (KRM) and inputting a rising or falling edge to the key interrupt input pins. See section 21, Key Interrupt Function (KINT) in User's Manual.

Table 1.11 Human machine interfaces (2/2)

Feature	Functional description
Capacitive Touch Sensing Unit (CTSU)	The CTSU measures the electrostatic capacitance of the touch sensor. Changes in the electrostatic capacitance are determined by the software, which enables the CTSU to detect whether a finger is in contact with the touch sensor. The electrode surface of the touch sensor is usually enclosed with an electrical conductor so that fingers do not come into direct contact with the electrodes. See section 50, Capacitive Touch Sensing Unit (CTSU) in User's Manual.

Table 1.12 Graphics

Feature	Functional description
Graphics LCD Controller (GLCDC)	The GLCDC provides multiple functions and supports various data formats and panels. Key GLCDC features include: • GPX bus master function for accessing graphics data • Superimposition of three planes (single color background plane, graphic 1 plane, and graphic 2 plane) • Support for many types of 32- or 16-bit per pixel graphics data and 8-, 4-, or 1-bit LUT data format • Digital interface signal output supporting a video image size of WVGA or greater. See section 57, Graphics LCD Controller (GLCDC) in User's Manual.
2D Drawing Engine (DRW)	The 2D Drawing Engine (DRW) provides flexible functions that can support almost any object geometry rather than being bound to only a few specific geometries such as lines, triangles, or circles. The edges of every object can be independently blurred or antialiased. Rasterization is executed at one pixel per clock on the bounding box of the object from left to right and top to bottom. The DRW can also raster from bottom to top to optimize the performance in certain cases. In addition, optimization methods are available to avoid rasterization of many empty pixels of the bounding box. The distances to the edges of the object are calculated by a set of edge equations for every pixel of the bounding box. These edge equations can be combined to describe the entire object. If a pixel is inside the object, it is selected for rendering. If it is outside it is discarded. If it is on the edge, an alpha value can be chosen proportional to the distance of the pixel to the nearest edge for antialiasing. Every pixel that is selected for rendering can be textured. The resulting aRGB quadruple can be modified by a general raster operation approach independently for each of the four channels. The aRGB quadruples can then be blended with one of the multiple blend modes of the DRW. The DRW provides two inputs (texture read and framebuffer read), and one output (framebuffer write). The internal color format is always aRGB (8888). The color formats from the inputs are converted to the internal format on read and a conversion back is made on write. See section 55, 2D Drawing Engine (DRW) in User's Manual.
JPEG Codec (JPEG)	The JPEG Codec (JPEG) incorporates a JPEG codec that conforms to the JPEG baseline compression and decompression standard. This provides high-speed compression of image data and high-speed decoding of JPEG data. See section 56, JPEG Codec in User's Manual.
Parallel Data Capture Unit (PDC)	One PDC unit is provided for communicating with external I/O devices, including image sensors, and transferring parallel data such as an image output from the external I/O device through the DTC or DMAC to the on-chip SRAM and external address spaces (the CS and SDRAM areas). See section 44, Parallel Data Capture Unit (PDC) in User's Manual.

Table 1.13 Data processing (1/2)

Feature	Functional description
Cyclic Redundancy Check (CRC) calculator	The CRC calculator generates CRC codes to detect errors in the data. The bit order of CRC calculation results can be switched for LSB-first or MSB-first communication. Additionally, various CRC-generating polynomials are available. The snoop function allows monitoring reads from and writes to specific addresses. This function is useful in applications that require CRC code to be generated automatically in certain events, such as monitoring writes to the serial transmit buffer and reads from the serial receive buffer. See section 40, Cyclic Redundancy Check (CRC) Calculator in User's Manual.
Data Operation Circuit (DOC)	The DOC compares, adds, and subtracts 16-bit data. See section 51, Data Operation Circuit (DOC) in User's Manual.

Table 1.13 Data processing (2/2)

Feature	Functional description
Sampling Rate Converter (SRC)	The SRC converts the sampling rate of data produced by various audio decoders, such as the WMA, MP3, and AAC. Both 16-bit stereo and monaural data are supported. The sampling rate of the input signal can be one of the following: • 8 kHz • 11.025 kHz • 12 kHz • 16 kHz • 22.05 kHz • 24 kHz • 32 kHz • 44.1 kHz • 48 kHz. The sampling rate of the output signal can be one of the following: • 8 kHz • 16 kHz • 32 kHz • 44.1 kHz • 48 kHz. Independent FIFOs are provided for input and output. In a typical application, a DMA controller can be used to transfer PCM audio data from SRAM, for example, to the SRC. Sample-converted audio data from the SRC can then be transferred using the DMA Controller to the SSI, from where it can be transmitted to an external audio codec. See section 42, Sampling Rate Converter (SRC) in User's Manual.

Table 1.14 Security

Feature	Functional description
Secure Crypto Engine 7 (SCE7)	• Security algorithms: - Symmetric algorithms: AES, 3DES, and ARC4 - Asymmetric algorithms: RSA, DSA, and DLP. • Other support features: - TRNG (True Random Number Generator) - Hash-value generation: SHA1, SHA224, SHA256, GHASH - 128-bit unique ID.

1.2 Block Diagram

Figure 1.1 shows the block diagram of the MCU superset. Some individual devices within the group have a subset of the features.

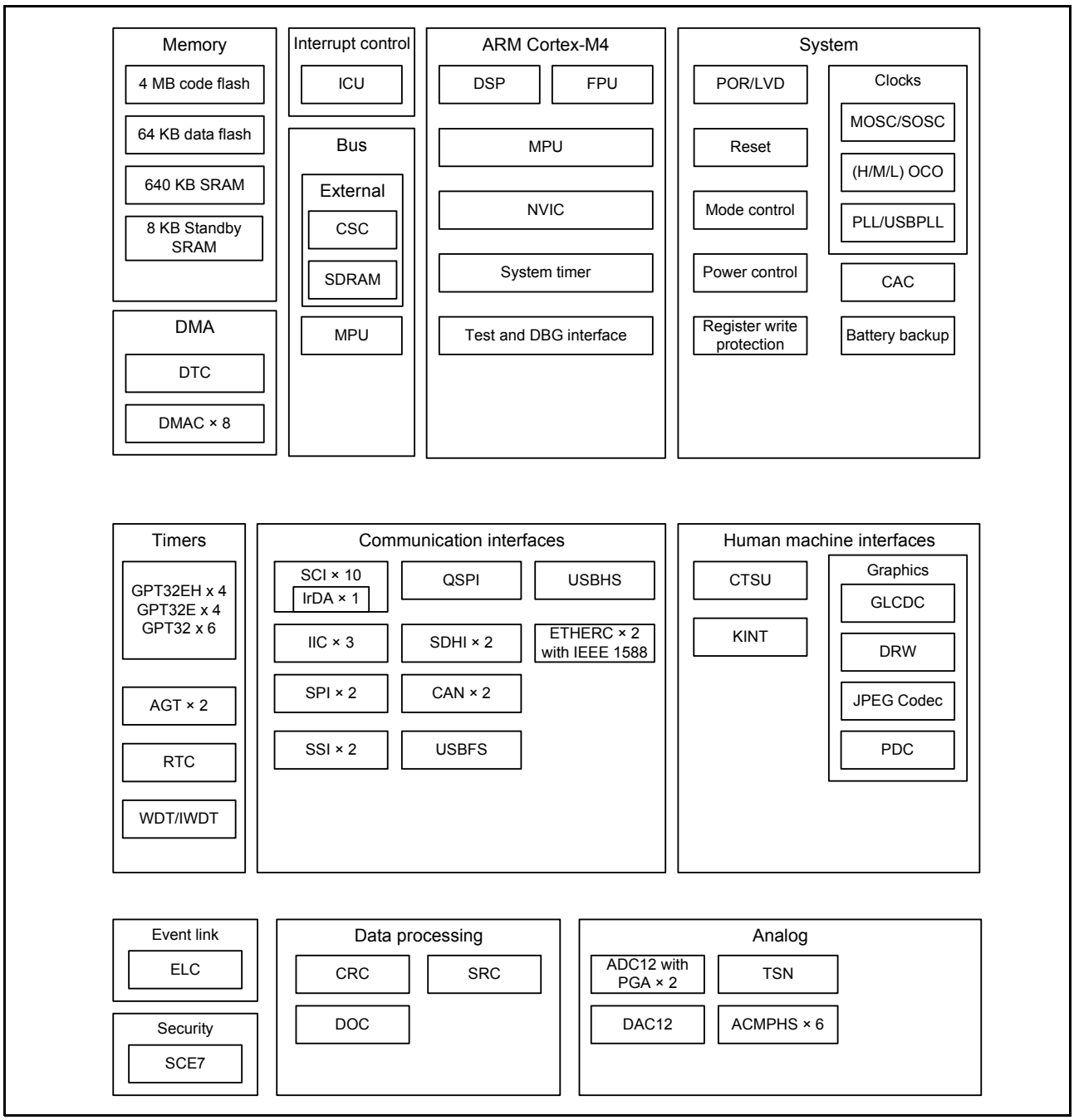

Figure 1.1 Block diagram

1.3 Part Numbering

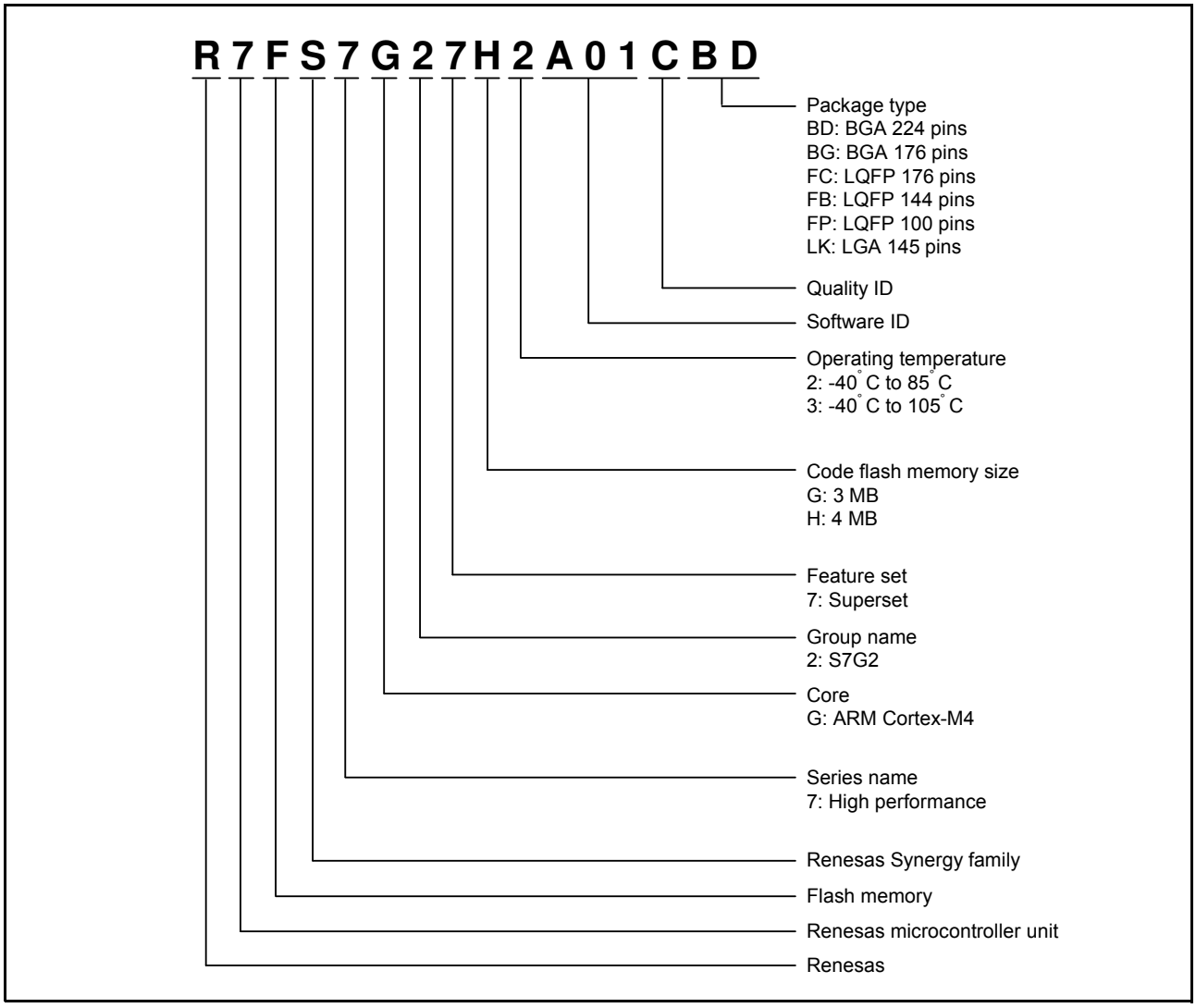

Figure 1.2 Part numbering scheme

1.4 Function Comparison

Table 1.15 Functional comparison

Function		Part numbers					
		R7FS7G27H2A01CBD/ R7FS7G27G2A01CBD	R7FS7G27H2A01CBG/ R7FS7G27G2A01CBG	R7FS7G27H3A01CFC/ R7FS7G27G3A01CFC	R7FS7G27H2A01CLK/ R7FS7G27G2A01CLK	R7FS7G27H3A01CFB/ R7FS7G27G3A01CFB	R7FS7G27G3A01CFP
Pin count		224	176	176	145	144	100
Package		BGA	BGA	LQFP	LGA	LQFP	LQFP
Code flash memory		4/3 MB					3 MB
Data flash memory		64 KB					
SRAM		640 KB					
	Parity	608 KB					
	DED	32 KB					
Standby SRAM		8 KB					
System	CPU clock	240 MHz					
	Backup registers	512 bytes					
Interrupt control	ICU	Yes					
Event link	ELC	Yes					
DMA	DTC	Yes					
	DMAC	8					
BUS	External bus	16-bit bus					8-bit bus
	SDRAM	Yes					No
Timers	GPT32EH	4	4	4	4	4	4
	GPT32E	4	4	4	4	4	3
	GPT32	6	6	6	6	6	5
	AGT	2	2	2	2	2	2
	RTC	Yes					
	WDT/IWDT	Yes					
Communication	SCI	10					
	IIC	3					2
	SPI	2					
	SSI	2					1
	QSPI	1					Dual-SPI 1
	SDHI	2					
	CAN	2					
	USBFS	Yes					
	USBHS	Yes			No		
	ETHERC	2	RMII 2	RMII 2	RMII 2/MII 1		RMII 1
Analog	ADC12	25	21	21	19	19	16
	DAC12	2					
	ACMPHS	6					
	TSN	Yes					
HMI	CTSU	18	12	12	18		12
	KINT	8					
Graphics	GLCDC	RGB888					RGB565
	DRW	Yes					
	JPEG	Yes					
	PDC	Yes					No
Data processing	CRC	Yes					
	DOC	Yes					
	SRC	Yes					
Security		SCE7					

1.5 Pin Functions

Table 1.16 Pin functions (1/5)

Function	Signal	I/O	Description
Power supply	VCC	Input	Power supply pin. Connect to the system power supply. Connect this pin to VSS through a 0.1-µF capacitor. Place the capacitor close to the pin.
	VCC_DCDC	Input	Switching regulator power supply pin.
	VLO	I/O	Switching regulator pin.
	VCL0 to VCL2	Input	Connect this pin to VSS through the smoothing capacitor used to stabilize the internal power supply. Place the capacitor close to the pin.
	VCL_F	Input	
	VSS	Input	Ground pin. Connect to the system power supply (0 V).
	VBATT	Input	Backup power pin.
Clock	XTAL	Output	Pins for a crystal resonator. An external clock signal can be input through the EXTAL pin.
	EXTAL	Input	
	XCIN	Input	Input/output pins for the sub-clock oscillator. Connect a crystal resonator between XCOUT and XCIN.
	XCOUT	Output	
	EBCLK	Output	Outputs the external bus clock for external devices.
	SDCLK	Output	Outputs the SDRAM-dedicated clock.
	CLKOUT	Output	Clock output pin.
Operating mode control	MD	Input	Pins for setting the operating mode. The signal levels on these pins must not be changed during operation mode transition on release from the reset state.
System control	RES	Input	Reset signal input pin. The MCU enters the reset state when this signal goes low.
CAC	CACREF	Input	Measurement reference clock input pin.
On-chip emulator	TMS	I/O	On-chip emulator or boundary scan pins.
	TDI	Input	
	TCK	Input	
	TDO	Output	
	TCLK	Output	This pin outputs the clock for synchronization with the trace data.
	TDATA0 to TDATA3	Output	These pins indicate that output from the TDATA0 to TDATA3 pins is valid.
	SWDIO	I/O	Serial wire debug data input/output pin.
	SWCLK	Input	Serial wire clock pin.
	SWO	Output	Serial wire trace output pin.
External bus interface	RD	Output	Strobe signal indicating that reading from the external bus interface space is in progress, active LOW.
	WR	Output	Strobe signal indicating that writing to the external bus interface space is in progress, in 1-write strobe mode, active LOW.
	WR0, WR1	Output	Strobe signals indicating that either group of data bus pins (D07 to D00 or D15 to D08) is valid in writing to the external bus interface space, in byte strobe mode, active LOW.
	BC0, BC1	Output	Strobe signals indicating that either group of data bus pins (D07 to D00 or D15 to D08) is valid in access to the external bus interface space, in 1-write strobe mode, active LOW.
	WAIT	Input	Input pin for wait request signals in access to the external space, active LOW.
	CS0 to CS7	Output	Select signals for CS areas, active LOW.
	A00 to A23	Output	Address bus.
	D00 to D15	I/O	Data bus.

Table 1.16 Pin functions (2/5)

Function	Signal	I/O	Description
SDRAM interface	CKE	Output	SDRAM clock enable signal.
	SDCS	Output	SDRAM chip select signal, active LOW.
	RAS	Output	SDRAM low address strobe signal, active LOW.
	CAS	Output	SDRAM column address strobe signal, active LOW.
	WE	Output	SDRAM write enable signal, active LOW.
	DQM0	Output	SDRAM I/O data mask enable signal for DQ07 to DQ00.
	DQM1	Output	SDRAM I/O data mask enable signal for DQ15 to DQ08.
	A00 to A15	Output	Address bus.
	DQ00 to DQ15	I/O	Data bus.
Interrupt	NMI	Input	Non-maskable interrupt request pin.
	IRQ0 to IRQ15	Input	Maskable interrupt request pins.
GPT	GTETRGA, GTETRGB, GTETRGC, GTETRGD	Input	External trigger input pins.
	GTIOC0A to GTIOC13A, GTIOC0B to GTIOC13B	I/O	Input capture, output compare, or PWM output pins.
	GTIU	Input	Hall sensor input pin U.
	GTIV	Input	Hall sensor input pin V.
	GTIW	Input	Hall sensor input pin W.
	GTOUUP	Output	Three-phase PWM output for BLDC motor control (positive U phase).
	GTOULO	Output	Three-phase PWM output for BLDC motor control (negative U phase).
	GTOVUP	Output	Three-phase PWM output for BLDC motor control (positive V phase).
	GTOVLO	Output	Three-phase PWM output for BLDC motor control (negative V phase).
	GTOWUP	Output	Three-phase PWM output for BLDC motor control (positive W phase).
	GTOWLO	Output	Three-phase PWM output for BLDC motor control (negative W phase).
AGT	AGTEE0, AGTEE1	Input	External event input enable signals.
	AGTIO0, AGTIO1	I/O	External event input and pulse output pins.
	AGTO0, AGTO1	Output	Pulse output pins.
	AGTOA0, AGTOA1	Output	Output compare match A output pins.
	AGTOB0, AGTOB1	Output	Output compare match B output pins.
RTC	RTCOUT	Output	Output pin for 1-Hz or 64-Hz clock.
	RTCIC0 to RTCIC2	Input	Time capture event input pins.
SCI	SCK0 to SCK9	I/O	Input/output pins for the clock (clock synchronous mode).
	RXD0 to RXD9	Input	Input pins for received data (asynchronous mode/clock synchronous mode).
	TXD0 to TXD9	Output	Output pins for transmitted data (asynchronous mode/clock synchronous mode).
	CTS0_RTS0 to CTS9_RTS9	I/O	Input/output pins for controlling the start of transmission and reception (asynchronous mode/clock synchronous mode), active LOW.
	SCL0 to SCL9	I/O	Input/output pins for the IIC clock (simple IIC).
	SDA0 to SDA9	I/O	Input/output pins for the IIC data (simple IIC).
	SCK0 to SCK9	I/O	Input/output pins for the clock (simple SPI).
	MISO0 to MISO9	I/O	Input/output pins for slave transmission of data (simple SPI).
	MOSI0 to MOSI9	I/O	Input/output pins for master transmission of data (simple SPI).
	SS0 to SS9	Input	Chip-select input pins (simple SPI), active LOW.
IIC	SCL0 to SCL2	I/O	Input/output pins for the clock.
	SDA0 to SDA2	I/O	Input/output pins for data.

Table 1.16 Pin functions (3/5)

Function	Signal	I/O	Description
SSI	SSISCK0	I/O	SSI serial bit clock pin.
	SSISCK1		
	SSIWS0	I/O	Word select pins.
	SSIWS1		
	SSITXD0	Output	Serial data output pins.
	SSIRXD0	Input	Serial data input pins.
	SSIDATA1	I/O	Serial data input/output pins.
	AUDIO_CLK	Input	External clock pin for audio (input oversampling clock).
SPI	RSPCKA, RSPCKB	I/O	Clock input/output pin.
	MOSIA, MOSIB	I/O	Input or output pins for data output from the master.
	MISOA, MISOB	I/O	Input or output pins for data output from the slave.
	SSLA0, SSLB0	I/O	Input or output pin for slave selection.
	SSLA1 to SSLA3, SSLB1 to SSLB3	Output	Output pin for slave selection.
QSPI	QSPCLK	Output	QSPI clock output pin.
	QSSL	Output	QSPI slave output pin.
	QIO0 to QIO3	I/O	Data0 to Data3.
CAN	CRX0, CRX1	Input	Receive data.
	CTX0, CTX1	Output	Transmit data.
USBFS	VCC_USB	Input	Power supply pins.
	VSS_USB	Input	Ground pins.
	USB_DP	I/O	D+ I/O pin of the USB on-chip transceiver. Connect this pin to the D+ pin of the USB bus.
	USB_DM	I/O	D– I/O pin of the USB on-chip transceiver. Connect this pin to the D– pin of the USB bus.
	USB_VBUS	Input	USB cable connection monitor pin. Connect this pin to VBUS of the USB bus. The VBUS pin status (connected or disconnected) can be detected when the USB module is operating as a function controller.
	USB_EXICEN	Output	Low-power control signal for external power supply (OTG) chip.
	USB_VBUSEN	Output	VBUS (5 V) supply enable signal for external power supply chip.
	USB_OVRCURA, USB_OVRCURB	Input	Connect the external overcurrent detection signals to these pins. Connect the VBUS comparator signals to these pins when the OTG power supply chip is connected.
	USB_ID	Input	Connect the MicroAB connector ID input signal to this pin during operation in OTG mode.
USBHS	VCC_USBHS	Input	Power supply pin.
	VSS1_USBHS	Input	Ground pin.
	VSS2_USBHS	Input	Ground pin.
	AVCC_USBHS	Input	Analog power supply pin for the USBHS.
	AVSS_USBHS	Input	Analog ground pin for the USBHS. Must be shorted to the PVSS_USBHS pin.
	PVSS_USBHS	Input	PLL circuit ground pin for the USBHS. Must be shorted to the AVSS_USBHS pin.
	USBHS_RREF	I/O	USBHS reference current source pin. Connect this pin to the AVSS_USBHS pin through a 2.2-kΩ resistor (±1%).
	USBHS_DP	I/O	USB bus D+ data pin.
	USBHS_DM	I/O	USB bus D- data pin.
	USBHS_EXICEN	Output	Connect this pin to the OTG power supply IC.
	USBHS_ID	Input	Connect this pin to the OTG power supply IC.
	USBHS_VBUSEN	Output	VBUS power enable signal for USB.
	USBHS_OVRCURA, USBHS_OVRCURB	Input	Overcurrent pin for USB.
	USBHS_VBUS	Input	USB cable connection monitor input pin.

Table 1.16 Pin functions (4/5)

Function	Signal	I/O	Description
ETHERC	REF50CK0, REF50CK1	Input	50-MHz reference clocks. These pins input reference signals for transmission/reception timing in RMII mode.
	RMII0_CRS_DV, RMII1_CRS_DV	Input	Indicate carrier detection signals and valid receive data on RMII_RXD1 and RMII_RXD0 in RMII mode.
	RMII0_TXD0, RMII0_TXD1, RMII1_TXD0, RMII1_TXD1	Output	2-bit transmit data in RMII mode.
	RMII0_RXD0, RMII0_RXD1, RMII1_RXD0, RMII1_RXD1	Input	2-bit receive data in RMII mode.
	RMII0_TXD_EN, RMII1_TXD_EN	Output	Output pins for data transmit enable signals in RMII mode.
	RMII0_RX_ER, RMII1_RX_ER	Input	Indicate an error occurred during reception of data in RMII mode.
	ET0_CRS, ET1_CRS	Input	Carrier detection/data reception enable signals.
	ET0_RX_DV, ET1_RX_DV	Input	Indicate valid receive data on ET_ERXD3 to ET_ERXD0.
	ET0_EXOUT, ET1_EXOUT	Input	General-purpose external output pins.
	ET0_LINKSTA, ET1_LINKSTA	Output	Input link status from the PHY-LSI.
	ET0_ETXD0 to ET0_ETXD3, ET1_ETXD0 to ET1_ETXD3	output	4 bits of MII transmit data.
	ET0_ERXD0 to ET0_ERXD3, ET1_ERXD0 to ET1_ERXD3	Input	4 bits of MII receive data.
	ET0_TX_EN, ET1_TX_EN	Output	Transmit enable signals. Function as signals indicating that transmit data is ready on ET_ETXD3 to ET_ETXD0.
	ET0_TX_ER, ET1_TX_ER	Output	Transmit error pins. Function as signals notifying the PHY_LSI of an error during transmission.
	ET0_RX_ER, ET1_RX_ER	Input	Receive error pins. Function as signals to recognize an error during reception.
	ET0_TX_CLK, ET1_TX_CLK	Input	Transmit clock pins. These pins input reference signals for output timing from ET_TX_EN, ET_ETXD3 to ET_ETXD0, and ET_TX_ER.
	ET0_RX_CLK, ET1_RX_CLK	Input	Receive clock pins. These pins input reference signals for input timing to ET_RX_DV, ET_ERXD3 to ET_ERXD0, and ET_RX_ER.
	ET0_COL, ET1_COL	Input	Input collision detection signals.
	ET0_WOL, ET1_WOL	Output	Receive Magic packets.
	ET0_MDC, ET1_MDC	Output	Output reference clock signals for information transfer through ET_MDIO.
	ET0_MDIO, ET1_MDIO	I/O	Input or output bidirectional signals for exchange of management data with PHY-LSI.
SDHI	SD0CLK, SD1CLK	Output	SD clock output pin.
	SD0CMD, SD1CMD	I/O	Command output pin and response input signal pin.
	SD0DAT0 to SD0DAT7, SD1DAT0 to SD1DAT7	I/O	SD and MMC data bus pins.
	SD0CD, SD1CD	Input	SD card detection pin.
	SD0WP, SD1WP	Input	SD write-protect signal.

Table 1.16 Pin functions (5/5)

Function	Signal	I/O	Description
Analog power supply	AVCC0	Input	Analog voltage supply pin for the analog. Connect this pin to VCC.
	AVSS0	Input	Analog ground pin. Connect this pin to VSS.
	VREFH0	Input	Analog reference voltage supply pin for the ADC12. Connect this pin to VCC when not using the ADC12.
	VREFL0	Input	Analog reference ground pin for the ADC12. Connect this pin to VSS when not using the ADC12.
	VREFH	Input	Reference voltage input pin for the ADC12 (unit 1) and D/A converter. This is used as the analog power supply for the respective modules. Connect this pin to VCC if the ADC12 (unit 1) or DAC12 is not in use.
	VREFL	Input	Reference ground pin for the ADC12 and D/A converter. This is used as the analog ground for the respective modules. Set this pin to the same potential as the VSS pin.
ADC12	AN000 to AN006, AN016 to AN021	Input	Input pins for the analog signals to be processed by the ADC12.
	AN100 to AN106, AN116 to AN120	Input	
	ADTRG0	Input	Input pins for the external trigger signals that start the A/D conversion, active LOW.
	ADTRG1	Input	
	PGAVSS000/PGAVSS100	Input	Differential input pins.
DAC12	DA0, DA1	Output	Output pins for the analog signals to be processed by the D/A converter.
ACMPHS	VCOUT	Output	Comparator output pin.
	IVREF0 to IVREF3	Input	Reference voltage input pin for comparator.
	IVCMP0 to IVCMP2	Input	Analog voltage input pins for comparator.
CTSU	TS00 to TS17	Input	Capacitive touch detection pins (touch pins).
	TSCAP	–	Secondary power supply pin for the touch driver.
KINT	KR00 to KR07	Input	A key interrupt (KINT) can be generated by inputting a falling edge to the key interrupt input pins.
I/O ports	P000 to P007	Input	General-purpose input pin.
	P008 to P011, P014, P015	I/O	General-purpose input/output pins.
	P100 to P115	I/O	General-purpose input/output pins.
	P200	Input	General-purpose iInput pin.
	P201 to P207, P212, P213	I/O	General-purpose input/output pins.
	P300 to P315	I/O	General-purpose input/output pins.
	P400 to P415	I/O	General-purpose input/output pins.
	P500 to P515	I/O	General-purpose input/output pins.
	P600 to P615	I/O	General-purpose input/output pins.
	P700 to P713	I/O	General-purpose input/output pins.
	P800 to P813	I/O	General-purpose input/output pins.
	P900 to P915	I/O	General-purpose input/output pins.
	PA00 to PA15	I/O	General-purpose input/output pins.
	PB00 to PB07	I/O	General-purpose input/output pins.
GLCDC	LCD_DATA00 to LCD_DATA23	Output	Data output pin for panel.
	LCD_TCON0 to LCD_TCON3	Output	Output pins for panel timing adjustment.
	LCD_CLK	Output	Panel clock output pin.
	LCD_EXTCLK	Input	Panel clock source input pin.
PDC	PIXCLK	Input	Image transfer clock pin.
	VSYNC	Input	Vertical synchronization signal pin.
	HSYNC	Input	Horizontal synchronization signal pin.
	PIXD0 to PIXD7	Input	8-bit image data pins.
	PCKO	Output	Output pin for dot clock.

1.6 Pin Assignments

Figure 1.3 to Figure 1.8 show the pin assignments.

R7FS7G2xxxA01CBD

	A	B	C	D	E	F	G	H	J	K	L	M	N	P	R	
15	P407	P408	P410	P708	VSS	USBHS_DM	PVSS_USBHS	P212/EXTAL	XCIN	VCL0	P707	P701	P403	P401	P511	15
14	USB_DP	USB_DM	P409	P411	P415	USBHS_DP	AVSS_USBHS	P213/XTAL	XCOUT	VBATT	P706	P700	P402	P514	P512	14
13	VCC_USB	VSS_USB	P207	P412	P709	VCC_USBHS	USBHS_RREF	AVCC_USBHS	VSS	PB01	P705	P405	P400	P513	P805	13
12	P202	P203	P205	P413	P711	VSS1_USBHS	VSS2_USBHS	VCC	PB05	PB03	VCC	P806	P002	P807	P000	12
11	P902	P901	P315	P204	P414	P712	PB07	PB06	PB02	P702	VSS	P004	P008	P001	P005	11
10	VCL1	VSS	VSS	VCC	P313	P710	P713	PB04	P704	P404	P003	P010	P011	P006	P009	10
9	VLO	VLO	P904	P903	P900	P314	P206	PB00	P406	P515	P007	P014	AVSS0	VREFL0	VREFH0	9
8	VCC_DCDC	P200	P201/MD	P910	P909	RES	P615	P913	P703	P809	VSS	P015	VREFL	AVCC0	VREFH	8
7	P911	P912	P311	P308	P908	P907	PA08	PA13	PA00	P808	VCC	P508	P510	VCC	VSS	7
6	P905	P312	P310	P307	P915	P906	PA11	PA02	PA01	P606	P812	P506	P507	P509	VCL2	6
5	VSS	VCC	P309	P306	P914	P300/TCK/SWCLK	PA12	PA10	PA03	P607	P811	P505	P502	P503	P504	5
4	VSS	VCC	P304	P305	P114	P608	P609	PA09	PA04	P107	P106	P804	P501	P803	P500	4
3	P303	P301	P112	P113	P115	P613	PA14	VCC	PA05	P603	P600	P105	P104	P810	P802	3
2	P302	P108/TMS/SWDIO	P110/TDI	VSS	P611	P612	PA15	VSS	PA06	P604	P601	VCC	P103	P800	P801	2
1	NC	P109/TDO	P111	VCC	P610	P614	P813	VCL_F	PA07	P605	P602	VSS	P102	P101	P100	1
	A	B	C	D	E	F	G	H	J	K	L	M	N	P	R	

Figure 1.3 Pin assignment for 224-pin BGA (top view)

R7FS7G2xxxA01CBG

	A	B	C	D	E	F	G	H	J	K	L	M	N	P	R	
15	P407	P409	P411	P414	VSS	USBHS_ DM	PVSS_ USBHS	P212 /EXTAL	XCIN	VCL0	P707	P703	P700	P405	P401	15
14	USB_DP	USB_DM	P410	P412	P415	USBHS_ DP	AVSS_ USBHS	P213 /XTAL	XCOUT	VBATT	P706	P701	P406	P402	P512	14
13	P204	VCC_ USB	VSS_ USB	P408	P413	VCC_ USBHS	USBHS_ RREF	AVCC_ USBHS	VSS	PB01	P704	P404	P400	P511	P805	13
12	P313	P202	P207	P206	P205	VSS1_ USBHS	VSS2_ USBHS	VCC	PB00	P705	P702	P403	P513	P806	P000	12
11	P900	P315	P314	P203								VCC	P001	P004	P002	11
10	VCL1	VSS	P901	VSS								VSS	P006	P008	P005	10
9	VLO	VLO	RES	VCC								P009	AVSS0	VREFL0	VREFH0	9
8	VCC_ DCDC	P201/MD	P200	P908								P010	AVCC0	VREFL	VREFH	8
7	P906	P905	P312	P907								VCC	VSS	P015	P014	7
6	P310	P309	P307	P311								P007	P507	P505	VCL2	6
5	P308	P305	VSS	VCC								P003	P503	P504	P506	5
4	P306	P304	P300/TCK /SWCLK	P111	VSS	P613	PA09	PA00	P607	VCC	VSS	VSS	VCC	P501	P502	4
3	P303	P302	P108/TMS SWDIO	P110/TDI	VCC	P610	VCC	VSS	P604	P603	P105	P102	P800	P804	P500	3
2	P301	P112	P114	P608	P611	P614	PA10	PA01	P605	P601	P107	P104	P101	P802	P803	2
1	P109/TDO	P113	P115	P609	P612	P615	PA08	VCL_F	P606	P602	P600	P106	P103	P100	P801	1
	A	B	C	D	E	F	G	H	J	K	L	M	N	P	R	

Figure 1.4 Pin assignment for 176-pin BGA (top view)

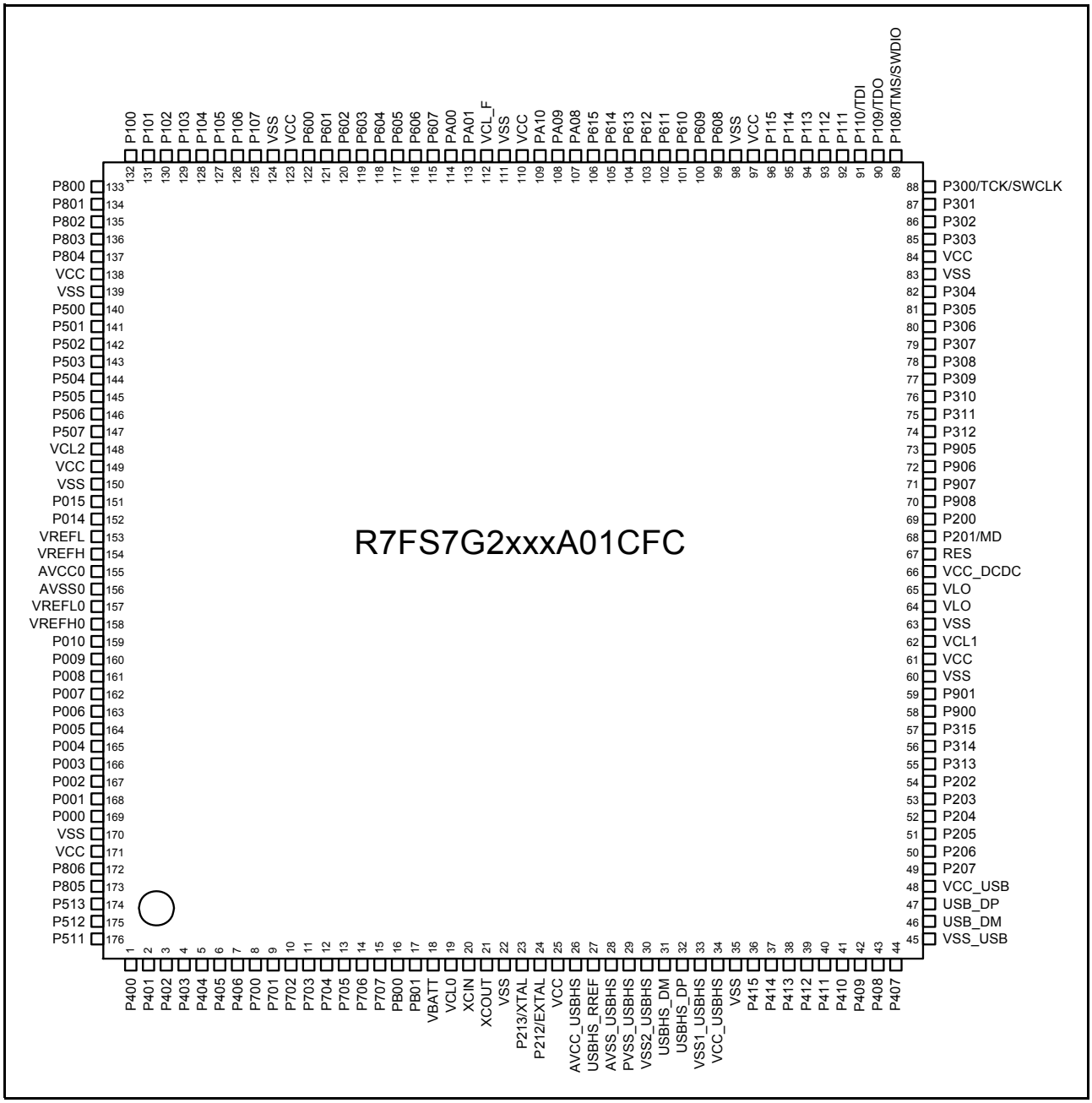

Figure 1.5 Pin assignment for 176-pin LQFP (top view)

R7FS7G2xxxA01CLK

	A	B	C	D	E	F	G	H	J	K	L	M	N	
13	P407	P409	P412	P708	P711	VCC	P212 /EXTAL	XCIN	VCL0	P702	P405	P402	P400	13
12	USB_DM	USB_DP	P410	P414	P710	VSS	P213 /XTAL	XCOUT	VBATT	P701	P404	P511	VCC	12
11	VCC_ USB	VSS_ USB	P207	P411	P415	P712	P705	P704	P703	P403	P401	P512	VSS	11
10	P205	P206	P204	P408	P413	P709	P713	P700	P406	P003	P000	P002	P001	10
9	P203	P313	P202	VSS						P004	P006	P009	P008	9
8	VCL1	VSS	P200	VCC						P005	AVSS0	VREFL0	VREFH0	8
7	VLO	VLO	RES	P310						P007	AVCC0	VREFL	VREFH	7
6	VCC_ DCDC	P201/MD	P312	P305						P505	P506	P015	P014	6
5	P309	P311	P308	P303	NC					P503	P504	VSS	VCC	5
4	P307	P306	P304	P109/TDO	P114	P608	P604	P600	P105	P500	P502	P501	VCL2	4
3	VSS	VCC	P301	P112	P115	P610	P614	P603	P107	P106	P104	VSS	VCC	3
2	P302	P300/TCK /SWCLK	P111	VCC	P609	P612	VSS	P605	P601	VCC	P800	P101	P801	2
1	P108/TMS /SWDIO	P110/TDI	P113	VSS	P611	P613	VCC	VCL_F	P602	VSS	P103	P102	P100	1
	A	B	C	D	E	F	G	H	J	K	L	M	N	

Figure 1.6 Pin assignment for 145-pin LGA (top view)

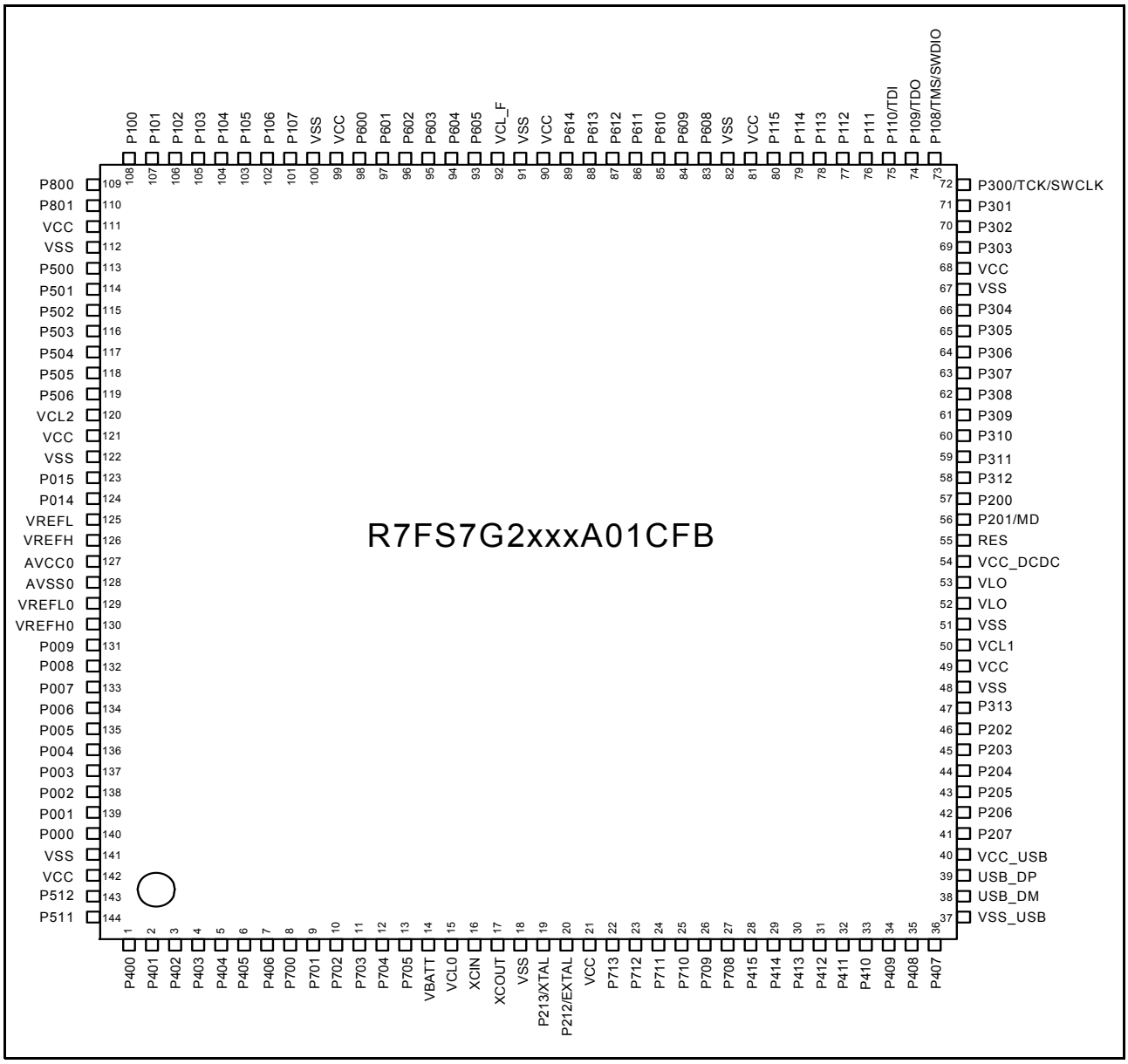

Figure 1.7 Pin assignment for 144-pin LQFP (top view)

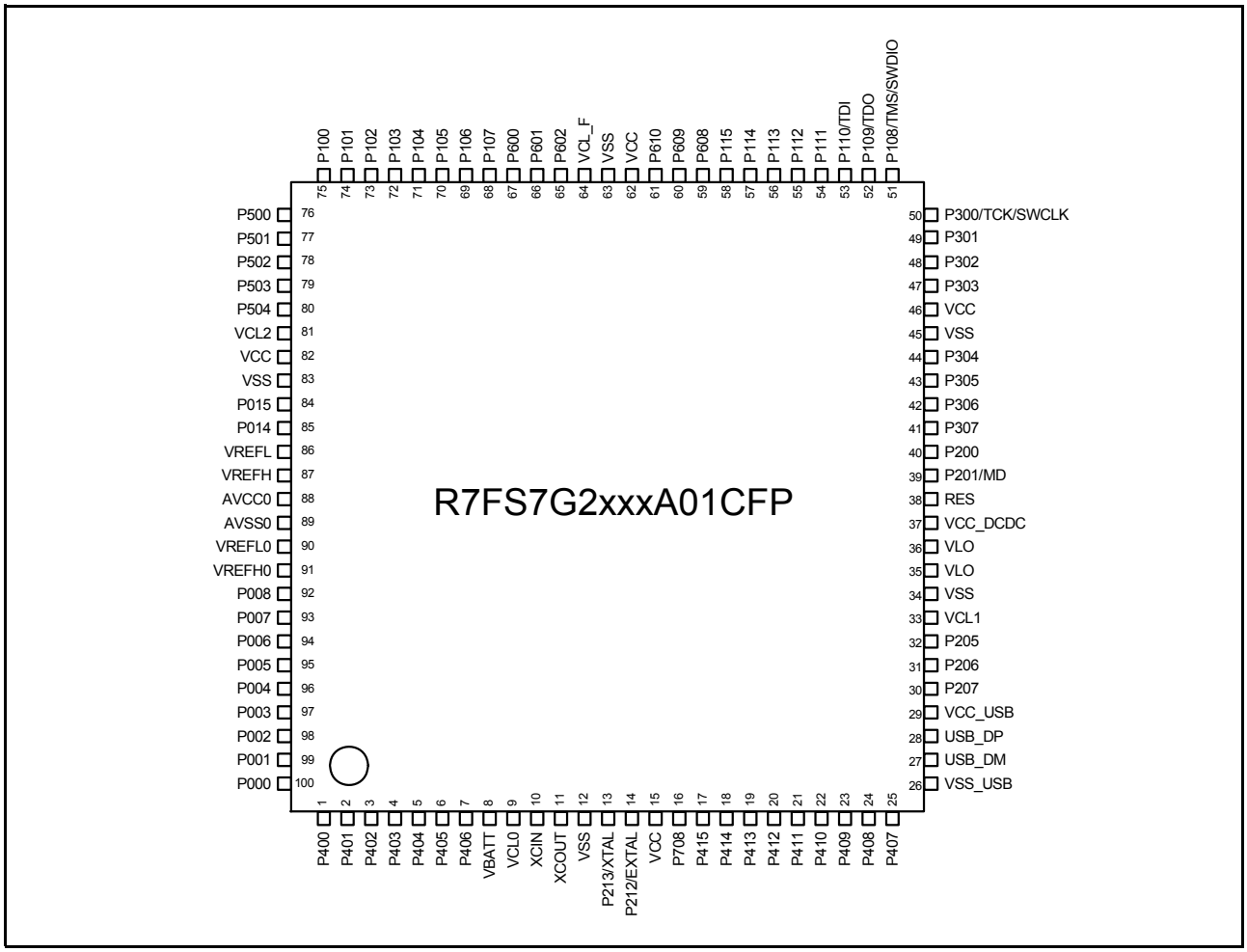

Figure 1.8 Pin assignment for 100-pin LQFP (top view)

1.7 Pin Lists

Table 1.17 Pin list (1/12)

Pin number						Power, System, Clock, Debug,	I/O port	Extbus		Timers				Communication interfaces										Analog		HMI		
BGA224	BGA176	LQFP176	LGA145	LQFP144	LQFP100			External bus	SDRAM	AGT	GPT	GPT	RTC	USBFS, CAN	SCI0,2,4,6,8 (30 MHz)	SCI1,3,5,7,9 (30 MHz)	IIC	SPI, QSPI	SSI	MII (25 MHz)	RMII (50 MHz)	USBHS	SDHI	ADC12	DAC12, ACMPHS	CTSU	Interrupt	GLCDC, PDC
N13	N13	1	N13	1	1	-	P400	-	-	-	-	GTIOC6A_A	-	-	SCK4_B	SCK7_A	SCL0_A	-	AUDIO_CLK	ET1_TX_CLK	-	-	-	ADTRG1_B	-	-	IRQ0	-
P15	R15	2	L11	2	2	-	P401	-	-	-	GETRGA_B	GTIOC6B_A	-	CTX0_B	CTS4_RTS4_B/SS4_B	TXD7_A/MOSI7_A/SDA7_A	SDA0_A	-	-	ET0_MDC	ET0_MDC	-	-	-	-	-	IRQ5-DS	-
N14	P14	3	M13	3	3	-	P402	-	-	AGTIO0_B/AGTIO1_B	-	-	RTCIC0	CRX0_B	-	RXD7_A/MISO7_A/SCL7_A	-	-	-	ET0_MDIO	ET0_MDIO	-	-	-	-	-	IRQ4-DS	-
N15	M12	4	K11	4	4	-	P403	-	-	AGTIO0_C/AGTIO1_C	-	GTIOC3A_B	RTCIC1	-	-	CTS7_RTS7_A/SS7_A	-	-	SSISCK0_A	ET1_MDC	ET1_MDC	-	-	-	-	-	-	PIXD7
K10	M13	5	L12	5	5	-	P404	-	-	-	-	GTIOC3B_B	RTCIC2	-	-	-	-	-	SSIWS0_A	ET1_MDIO	ET1_MDIO	-	-	-	-	-	-	PIXD6
M13	P15	6	L13	6	6	-	P405	-	-	-	-	GTIOC1A_B	-	-	-	-	-	-	SSITXD0_A	ET1_TX_EN	RMII1_TXD_EN	-	-	-	-	-	-	PIXD5
J9	N14	7	J10	7	7	-	P406	-	-	-	-	GTIOC1B_B	-	-	-	-	-	-	SSIRXD0_A	ET1_RX_ER	RMII1_TXD1	-	-	-	-	-	-	PIXD4
M14	N15	8	H10	8	-	-	P700	-	-	-	-	GTIOC5A_B	-	-	-	-	-	-	-	ET1_ETXD1	RMII1_TXD0	-	-	-	-	-	-	PIXD3
M15	M14	9	K12	9	-	-	P701	-	-	-	-	GTIOC5B_B	-	-	-	-	-	-	-	ET1_ETXD0	REF50CK1	-	-	-	-	-	-	PIXD2
K11	L12	10	K13	10	-	-	P702	-	-	-	-	GTIOC6A_B	-	-	-	-	-	-	-	ET1_ERXD1	RMII1_RXD0	-	-	-	-	-	-	PIXD1
J8	M15	11	J11	11	-	-	P703	-	-	-	-	GTIOC6B_B	-	-	-	-	-	-	-	ET1_ERXD0	RMII1_RXD1	-	-	-	-	-	-	PIXD0
J10	L13	12	H11	12	-	-	P704	-	-	-	-	-	-	-	-	-	-	-	-	ET1_RX_CLK	RMII1_RX_ER	-	-	-	-	-	-	HSYNC
L13	K12	13	G11	13	-	-	P705	-	-	-	-	-	-	-	-	-	-	-	-	ET1_CRS	RMII1_CRS_DV	-	-	-	-	-	-	PIXCLK
L14	L14	14	-	-	-	-	P706	-	-	-	-	-	-	-	-	RXD3_B/MISO3_B/SCL3_B	-	-	-	-	-	USBHS_OVRCURB	-	-	-	-	IRQ7	-
L15	L15	15	-	-	-	-	P707	-	-	-	-	-	-	-	-	TXD3_B/MOSI3_B/SDA3_B	-	-	-	-	-	USBHS_OVRCURA	-	-	-	-	IRQ8	-

Table 1.17 Pin list (2/12)

Pin number						Power, System, Clock, Debug,	I/O port	Extbus		Timers				Communication interfaces										Analog		HMI		
BGA224	BGA176	LQFP176	LGA145	LQFP144	LQFP100			External bus	SDRAM	AGT	GPT	GPT	RTC	USBFS, CAN	SCI0,2,4,6,8 (30 MHz)	SCI1,3,5,7,9 (30 MHz)	IIC	SPI, QSPI	SSI	MII (25 MHz)	RMII (50 MHz)	USBHS	SDHI	ADC12	DAC12, ACMPHS	CTSU	Interrupt	GLCDC, PDC
H9	J12	16	-	-	-	-	PB00	-	-	-	-	-	-	-	-	SCK3_B	-	-	-	-	USBHS_VBUSEN	-	-	-	-	-	
J11	-	-	-	-	-	-	PB02	-	-	-	-	-	-	-	CTS8_RTS8_B/SS8_B	-	-	-	-	ET1_RX_DV	-	-	-	-	-	-	
K12	-	-	-	-	-	-	PB03	-	-	-	-	-	-	-	SCK8_B	-	-	-	-	ET1_COL	-	-	-	-	-	-	
H10	-	-	-	-	-	-	PB04	-	-	-	-	-	-	-	TXD8_B/MOSI8_B/SDA8_B	-	-	-	-	ET1_ERXD2	-	-	-	-	-	-	IRQ12
K13	K13	17	-	-	-	-	PB01	-	-	-	-	-	-	-	-	CTS3_RTS3_B/SS3_B	-	-	-	-	-	-	USBHS_VBUS	-	-	-	-	
J12	-	-	-	-	-	-	PB05	-	-	-	-	-	-	-	RXD8_B/MISO6_B/SCL6_B	-	-	-	-	ET1_ERXD3	-	-	-	-	-	-	IRQ13
H11	-	-	-	-	-	-	PB06	-	-	-	-	-	-	-		-	-	-	-	ET1_WOL	ET1_WOL	-	-	-	-	-	-
G11	-	-	-	-	-	-	PB07	-	-	-	-	-	-	-		-	-	-	-	ET1_LINKSTA	ET1_LINKSTA	-	-	-	-	-	-
K14	K14	18	J12	14	8	VBATT	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
K15	K15	19	J13	15	9	VCL0	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
J15	J15	20	H13	16	10	XCIN	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
J14	J14	21	H12	17	11	XCOUT	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
J13	J13	22	F12	18	12	VSS	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
H14	H14	23	G12	19	13	XTAL	P213	-	-	-	GTETRGC_A	-	-	-	-	TXD1_A/MOSI1_A/SDA1_A	-	-	-	-	-	-	-	ADTRG1_A	-	-	IRQ2	-
H15	H15	24	G13	20	14	EXTAL	P212	-	-	AGTEE1	GTETRGD_A	-	-	-	-	RXD1_A/MISO1_A/SCL1_A	-	-	-	-	-	-	-	-	-	-	IRQ3	-
H12	H12	25	F13	21	15	VCC	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
H13	H13	26	-	-	-	AVCC_USBHS	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
G13	G13	27	-	-	-	USBHS_RREF	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-

Table 1.17 Pin list (3/12)

Pin number						Power, System, Clock, Debug,	I/O port	Extbus		Timers				Communication interfaces										Analog		HMI		
BGA224	BGA176	LQFP176	LGA145	LQFP144	LQFP100			External bus	SDRAM	AGT	GPT	GPT	RTC	USBFS, CAN	SCI0,2,4,6,8 (30 MHz)	SCI1,3,5,7,9 (30 MHz)	IIC	SPI, QSPI	SSI	MII (25 MHz)	RMII (50 MHz)	USBHS	SDHI	ADC12	DAC12, ACMPHS	CTSU	Interrupt	GLCDC, PDC
G14	G14	28	-	-	-	AVSS_USBHS	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
G15	G15	29	-	-	-	PVSS_USBHS	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
G12	G12	30	-	-	-	VSS2_USBHS	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
F15	F15	31	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	USBHS_DM	-	-	-	-	-	-
F14	F14	32	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	USBHS_DP	-	-	-	-	-	-
F12	F12	33	-	-	-	VSS1_USBHS	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
F13	F13	34	-	-	-	VCC_USBHS	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-
E15	E15	35	-	-	-	VSS	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-	-		-	-
G10	-	-	G10	22	-	-	P713	-	-	-	-	GTIOC2A_B	-	-	-	-	-	-	-	ET1_EXOUT	ET1_EXOUT	-	-	-	-	TS17	-	-
F11	-	-	F11	23	-	-	P712	-	-	-	-	GTIOC2B_B	-	-	-	-	-	-	-	-	-	-	-	-	-	TS16	-	-
E12	-	-	E13	24	-	-	P711	-	-	-	-	-	-	-	-	CTS1_RTS1_B/SS1_B	-	-	-	ET0_TX_CLK	-	-	-	-	-	TS15	-	-
F10	-	-	E12	25	-	-	P710	-	-	-	-	-	-	-	-	SCK1_B	-	-	-	ET0_TX_ER	-	-	-	-	-	TS14	-	-
E13	-	-	F10	26	-	-	P709	-	-	-	-	-	-	-	-	TXD1_B/MOSI1_B/SDA1_B	-	-	-	ET0_ETXD2	-	-	-	-	-	TS13	IRQ10	-
D15	-	-	D13	27	16	CACREF_B	P708	-	-	-	-	-	-	-	-	RXD1_B/MISO1_B/SCL1_B	-	SSLA3_B	-	ET0_ETXD3	-	-	-	-	-	TS12	IRQ11	-
E14	E14	36	E11	28	17	-	P415	-	-	-	-	-	-	-	-	-	-	SSLA2_B	-	ET0_TX_EN	RMII0_TXD_EN	-	-	-	-	TS11	-	-
E11	D15	37	D12	29	18	-	P414	-	-	-	-	-	-	-	-	-	-	SSLA1_B	-	ET0_RX_ER	RMII0_TXD1	-	SD0WP	-	-	TS10	-	-
D12	E13	38	E10	30	19	-	P413	-	-	-	GTOUUP_B	-	-	-	CTS0_RTS0_B/SS0_B	-	-	SSLA0_B	-	ET0_ETXD1	RMII0_TXD0	-	SD0CLK	-	-	TS09	-	-
D13	D14	39	C13	31	20	-	P412	-	-	-	GTOULO_B	-	-	-	SCK0_B	-	-	RSPCKA_B	-	ET0_ETXD0	REF50CK0	-	SD0CMD	-	-	TS08	-	-